



Material Content Data Sheet



Sales Product Name		BSP752T		Issued		29. August 2013		
MA#		MA001056428						
Package		PG-DSO-8-24		Weight*		83.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.188	2.63	2.63	26271	26271
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8610	
wire	non noble metal	copper	7440-50-8	29.121	34.96	35.87	349622	358771
	noble metal	gold	7440-57-5	0.389	0.47	0.47	4671	4671
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1168
plastics	plastics	epoxy resin	-	4.473	5.37		53708	
		silicondioxide	60676-86-0	44.054	52.88	58.37	528906	583782
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9771	9771
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7807	7807
glue	plastics	epoxy resin	-	0.130	0.16		1562	
		noble metal	silver	7440-22-4	0.613	0.74	0.90	7365
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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